

MT29F32G08CBACAL73A3WC1 Information


For Reference Only

Part Number [MT29F32G08CBACAL73A3WC1](#)
Manufacturer Micron Technology Inc.
Category Integrated Circuits (ICs)
Memory
Description IC FLASH 32GBIT WAFER
Package Die
 For the pricing/inventory/lead time, please contact us
 Website: <https://www.heisener.com>
 E-mail: salesdept@heisener.com



[Request a Quote](#)

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.


MT29F32G08CBACAL73A3WC1 Specifications

Manufacturer Part Number	MT29F32G08CBACAL73A3WC1
Manufacturer	Micron Technology Inc.
Category	Integrated Circuits (ICs) Memory
Package	Die
Series	-
Memory Type	Non-Volatile
Memory Format	FLASH
Technology	FLASH - NAND
Memory Size	32Gb (4G x 8)
Memory Interface	Parallel
Clock Frequency	-
Write Cycle Time - Word, Page	-
Access Time	-
Voltage - Supply	2.7 V ~ 3.6 V
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	Die
Supplier Device Package	Die

[Report errors?](#)

MT29F32G08CBACAL73A3WC1 Guarantees



Quality Guarantees

We provide 90 days warranty. *

If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.



Service Guarantees

We guarantee 100% customer satisfaction.

Our experienced sales team and tech support team back our services to satisfy all our customers.

MT29F32G08CBACAL73A3WC1 Payment Methods



MT29F32G08CBACAL73A3WC1 Shipping Methods



If you have any question about MT29F32G08CBACAL73A3WC1, please do not hesitate to contact us!

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